

Silicon PIN Photodiode



DESCRIPTION

VEMD8080 is a high speed and high sensitive PIN photodiode with enhanced sensitivity for visible light. It is a low profile surface-mount device (SMD) including the chip with a 4.5 mm² sensitive area detecting visible and near infrared radiation.

FEATURES

- Package type: surface-mount
- Package form: top view
- Dimensions (L x W x H in mm): 4.8 x 2.5 x 0.48
- Radiant sensitive area (in mm²): 4.5
- 0.48 mm low profile package
- Enhanced sensitivity for visible light
- Suitable for visible and near infrared radiation
- Fast response times
- Angle of half sensitivity: $\phi = \pm 65^\circ$
- Floor life: 168 h, MSL 3, according to J-STD-020
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



RoHS
COMPLIANT
HALOGEN
FREE
GREEN
(5-2008)

APPLICATIONS

- High speed photo detector
- Wearables

PRODUCT SUMMARY

COMPONENT	I_{ra} (μA)	ϕ (deg)	$\lambda_{0.1}$ (nm)
VEMD8080	28	± 65	350 to 1100

Note

- Test conditions see table “Basic Characteristics”

ORDERING INFORMATION

ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM
VEMD8080	Tape and reel	MOQ: 5000 pcs, 5000 pcs/reel	Top view

Note

- MOQ: minimum order quantity

ABSOLUTE MAXIMUM RATINGS ($T_{amb} = 25^\circ\text{C}$, unless otherwise specified)

PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Reverse voltage		V_R	20	V
Junction temperature		T_j	85	$^\circ\text{C}$
Operating temperature range		T_{amb}	-40 to +85	$^\circ\text{C}$
Storage temperature range		T_{stg}	-40 to +85	$^\circ\text{C}$
Soldering temperature	According to reflow solder profile Fig. 8	T_{sd}	260	$^\circ\text{C}$
Thermal resistance junction-to-ambient		R_{thJA}	350	K/W
ESD safety HBM	± 2000 V, 1.5 kΩ, 100 pF, 3 pulses	ESD_{HBM}	≥ 2	kV

BASIC CHARACTERISTICS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Forward voltage	$I_F = 50\text{ mA}$	V_F	-	1.2	1.6	V
Breakdown voltage	$I_R = 100\text{ }\mu\text{A}$, $E = 0$	$V_{(BR)}$	20	-	-	V
Reverse dark current	$V_R = 10\text{ V}$, $E = 0$	I_{ro}	-	0.2	10	nA
Diode capacitance	$V_R = 0\text{ V}$, $f = 1\text{ MHz}$, $E = 0$	C_D	-	47	-	pF
	$V_R = 3\text{ V}$, $f = 1\text{ MHz}$, $E = 0$	C_D	-	17	40	pF
Open circuit voltage	$E_e = 1\text{ mW/cm}^2$, $\lambda = 950\text{ nm}$	V_o	-	320	-	mV
Temperature coefficient of V_o	$E_e = 1\text{ mW/cm}^2$, $\lambda = 950\text{ nm}$	TK_{V_o}	-	-3.0	-	mV/K
Short circuit current	$E_e = 1\text{ mW/cm}^2$, $\lambda = 950\text{ nm}$	I_k	-	32	-	μA
Temperature coefficient of I_k	$E_e = 1\text{ mW/cm}^2$, $\lambda = 950\text{ nm}$	TK_{I_k}	-	0.1	-	%/K
Reverse light current	$E_e = 1\text{ mW/cm}^2$, $\lambda = 850\text{ nm}$, $V_R = 5\text{ V}$	I_{ra}	23	28	33	μA
	$E_e = 0.25\text{ mW/cm}^2$, $\lambda = 525\text{ nm}$, $V_R = 5\text{ V}$	I_{ra}	3.4	4.4	5.3	μA
Angle of half sensitivity		ϕ	-	± 65	-	deg
Wavelength of peak sensitivity		λ_p	-	850	-	nm
Range of spectral bandwidth		$\lambda_{0.1}$	-	350 to 1100	-	nm
Rise time	$V_R = 10\text{ V}$, $R_L = 1\text{ k}\Omega$, $\lambda = 830\text{ nm}$	t_r	-	70	-	ns
Fall time	$V_R = 10\text{ V}$, $R_L = 1\text{ k}\Omega$, $\lambda = 830\text{ nm}$	t_f	-	70	-	ns

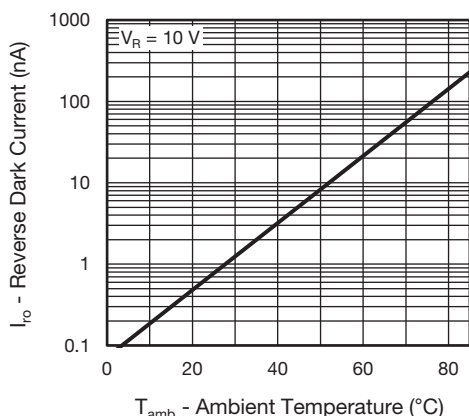
BASIC CHARACTERISTICS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)


Fig. 1 - Reverse Dark Current vs. Ambient Temperature

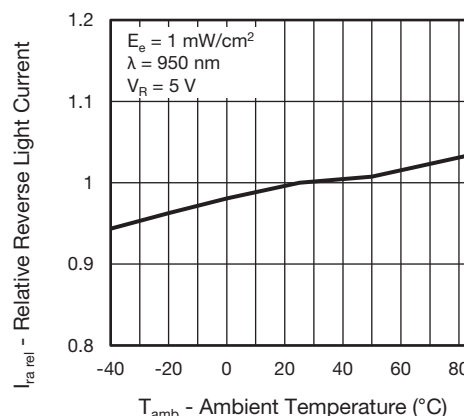


Fig. 2 - Relative Reverse Light Current vs. Ambient Temperature

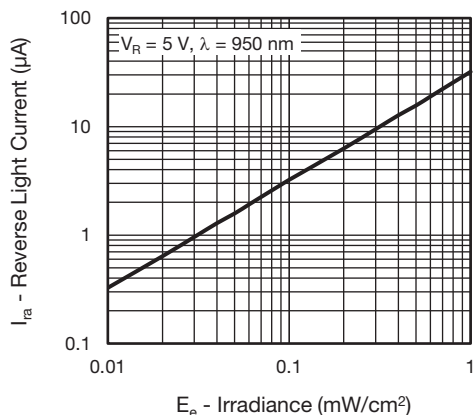


Fig. 3 - Reverse Light Current vs. Irradiance

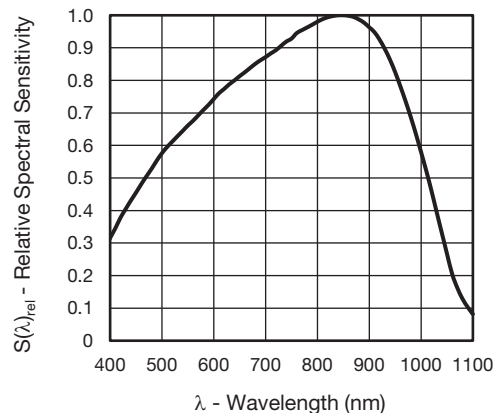


Fig. 5 - Relative Spectral Sensitivity vs. Wavelength

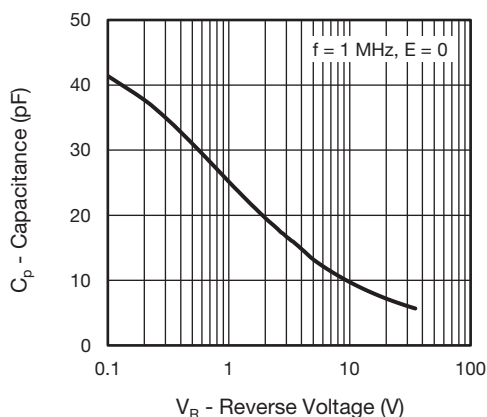


Fig. 4 - Diode Capacitance vs. Reverse Voltage

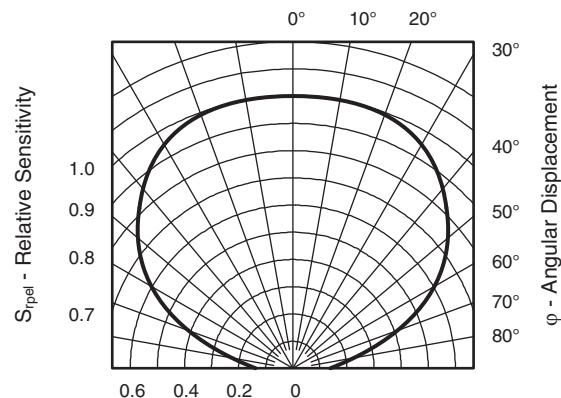
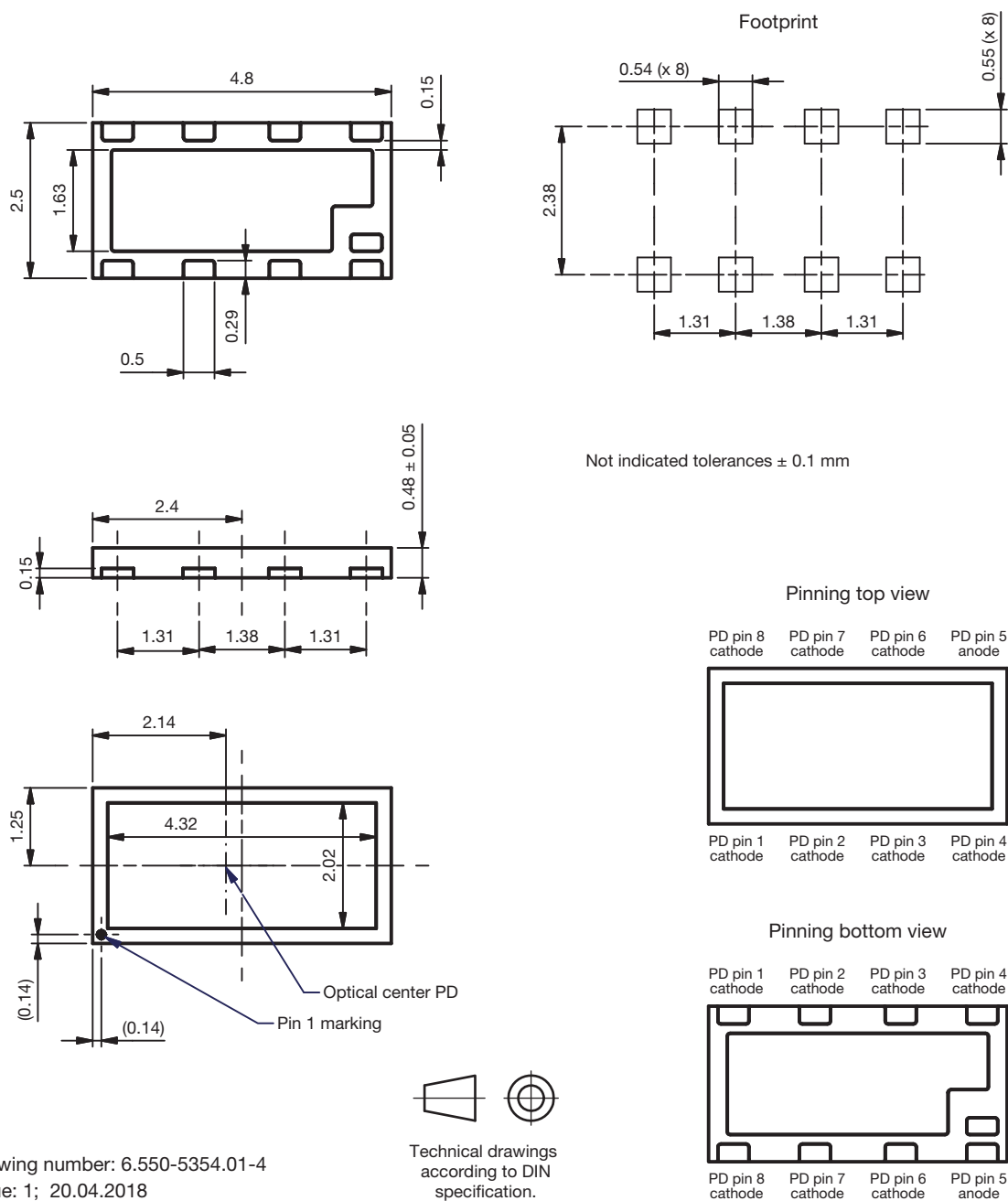


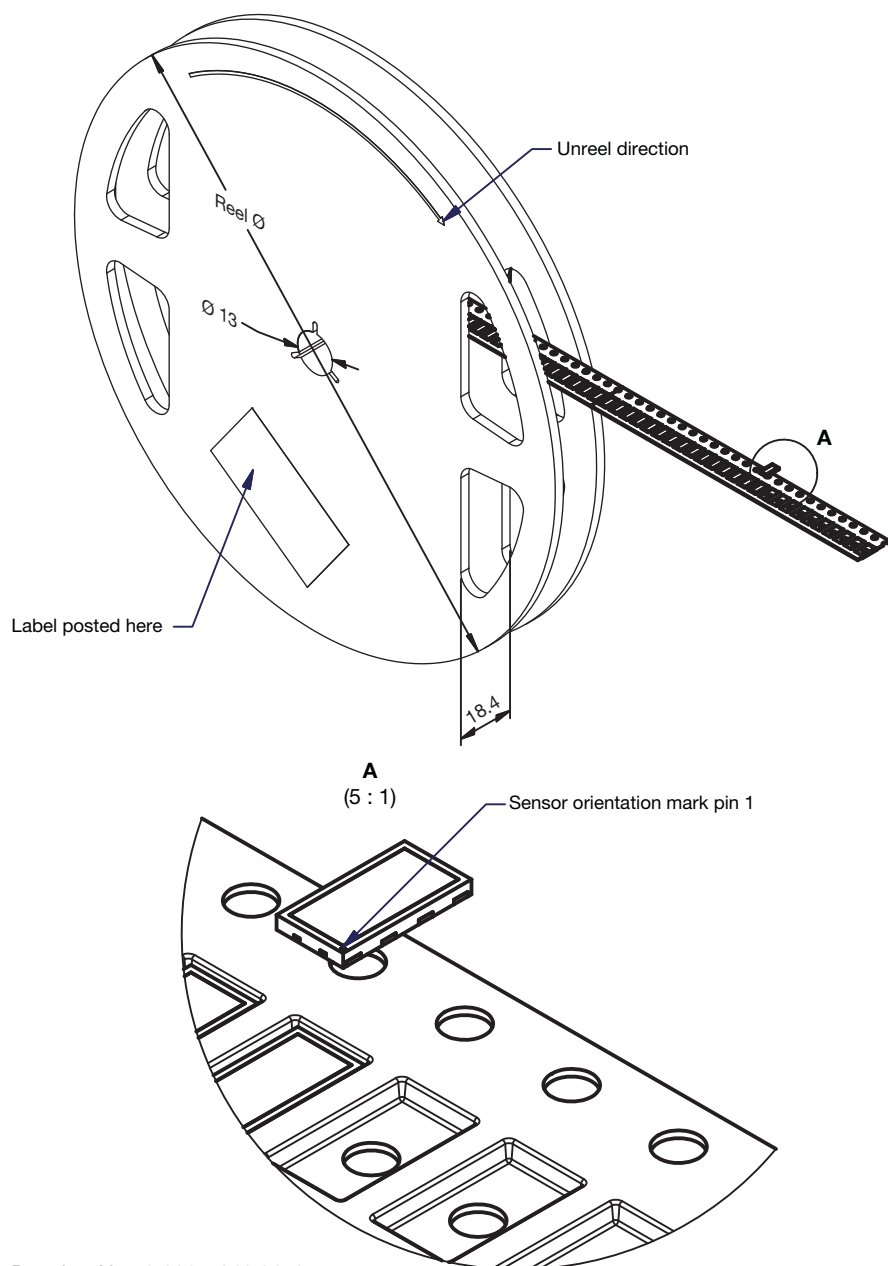
Fig. 6 - Relative Sensitivity vs. Angular Displacement

PACKAGE DIMENSIONS in millimeters


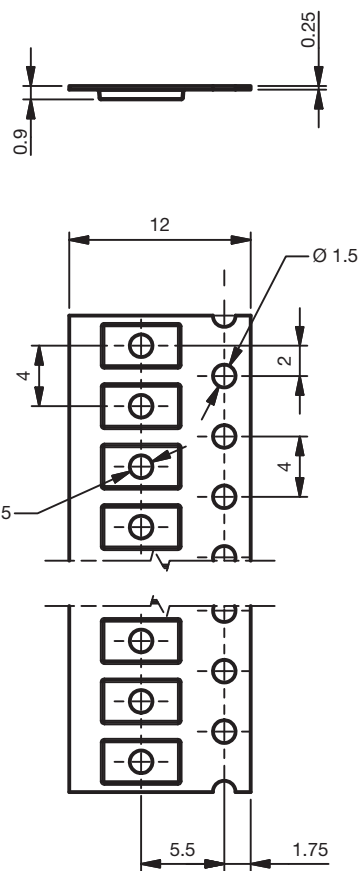
Drawing number: 6.550-5354.01-4
Issue: 1; 20.04.2018



TAPE AND REEL DIMENSIONS in millimeters



Non tolerated dimensions ± 0.1 mm
Reel design is representative for different types



Drawing-No.: 9.800-5146.01-4
Issue: 1; 20.04.2018

SOLDER PROFILE

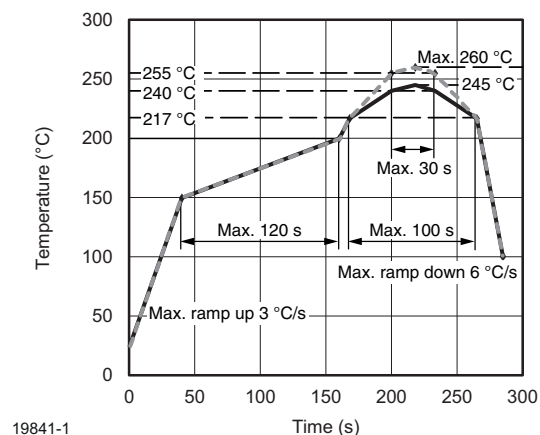


Fig. 7 - Lead (Pb)-free Reflow Solder Profile
According to J-STD-020D

DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

FLOOR LIFE

Time between soldering and removing from MBB must not exceed the time indicated in J-STD-020:

Moisture sensitivity: level 3

Floor life: 168 h

Conditions: $T_{amb} < 30\text{ °C}$, $RH < 60\%$

DRYING

In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or recommended conditions:

192 h at $40\text{ °C} (+ 5\text{ °C})$, $RH < 5\%$

or

96 h at $60\text{ °C} (+ 5\text{ °C})$, $RH < 5\%$



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